



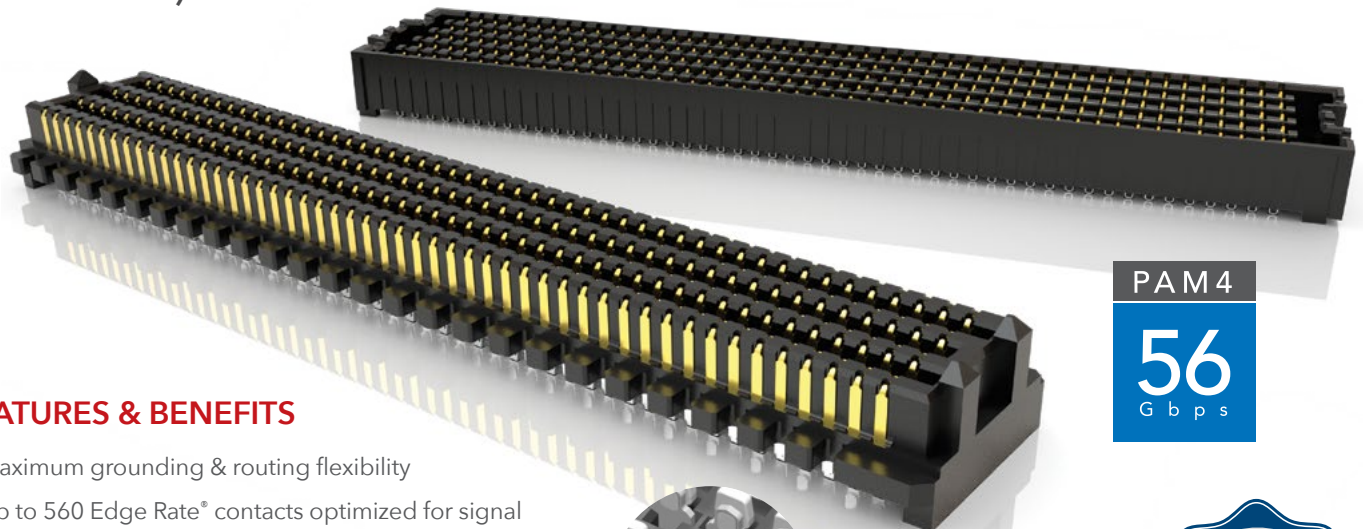
**THE DATASHEET OF
SEAF-30-01-L-06-2-RA-TR**





HIGH-DENSITY OPEN-PIN-FIELD ARRAYS

(1.27 mm) .050" PITCH



FEATURES & BENEFITS

- Maximum grounding & routing flexibility
- Up to 560 Edge Rate® contacts optimized for signal integrity performance.
- 7 mm to 40 mm stack heights
- Variety of designs and options: Right-Angle, Guide Posts, 85 Ω Elevated Risers, 85 Ω Tuned, Press-Fit and Press-Fit Right-Angle, Guide Post Field Termination Kits
- Cable mates (SEAC Series) and Jack Screw Standoffs (JSO Series) also available
- Standards: VITA 47, VITA 57.1 FMC, VITA 57.4 FMC+, VITA 74 VNX, PISMO™ 2
- Supports high-speed protocols such as Ethernet, PCI Express®, Fibre Channel & InfiniBand™
- Severe Environment Testing qualified (SEAM/SEAF); aligns with MIL-DTL-55302. Visit samtec.com/set



Solder Charges



(1.12 mm) .044" Nominal Wipe

EDGE RATE
CONTACT

PAM 4
56
Gbps



MAXIMUM GROUNDING & ROUTING FLEXIBILITY



Differential Pair Single-Ended Power

SERIES	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING	OPERATING TEMP RANGE	CURRENT RATING	VOLTAGE RATING	LEAD-FREE SOLDERABLE
SEAM/SEAF	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	2.7 A (10 pins powered)	240 VAC	Yes
SEAM-RA/SEAF-RA	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	1.9 A (10 pins powered)	260 VAC	Yes
SEAM-GP	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	2.7 A (10 pins powered)	240 VAC	Yes
SEAMP/SEAFP	Natural High Temp Nylon	Copper Alloy (SEAMP) BeCu Alloy (SEAFP)	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	1.9 A (6 pins powered)	225 VAC	Not Available
SEAR	Black LCP	Hard Gold Plated	Au over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	Contact Samtec	240 VAC	Not Available
SEAMI	Black LCP	Copper Alloy	Au or Sn over 50 μ" (1.27 μm) Ni	-55 °C to +125 °C	Not Available	Not Available	Yes

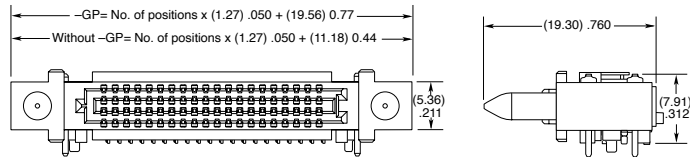
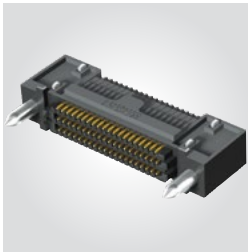
Note: Some lengths, styles and options are non-standard, non-returnable

(1.27 mm) .050" PITCH • RIGHT-ANGLE & GUIDE POST

SERIES	POSITIONS PER ROW	01	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	RA	OPTIONS	"X"R
SEAM Right-Angle Terminal	-20		-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail	-04	-1 = Tin/Lead Alloy Solder Charge		-GP = Guide Post/Hole	-TR = Tape & Reel
	-30			-06			-2 = Lead-Free Solder Charge	-K = Polyimide Film Pick & Place Pad
SEAF Right-Angle Socket	-40		-S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail	-08	-08 & -10 Row options require fixturing to process		-LP Latch Post (Available with SEAF in -06 Row with 30 positions only; Required for mating to SEAC)	
	-50			-10				

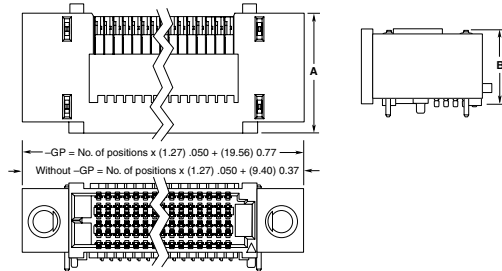
SEAM-RA

Board Mates:
SEAF, SEAF-RA,
SEAFP



SEAF-RA

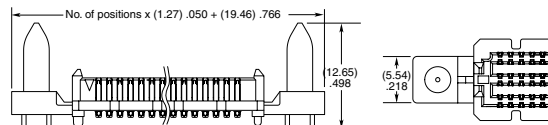
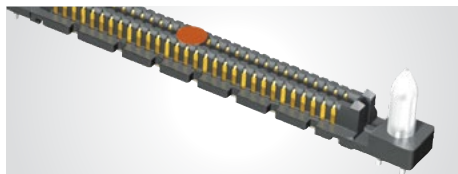
Board Mates:
SEAM, SEAMP



NO. PINS PER ROW	A	B
-04	(13.77) .542	(7.91) .311
-06	(16.31) .642	(10.45) .411
-08	(18.85) .742	(12.99) .511
-10	(21.39) .842	(15.53) .611

View complete specifications at: samtec.com?SEAM-RA & samtec.com?SEAF-RA

SERIES	POSITIONS PER ROW	02.0	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	A	GP	K	"X"R
SEAM Terminal with Guide post	-20, -30, -40, -50		-L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail	-04	-1 = Tin/Lead Alloy Solder Charge				-TR = Tape & Reel
				-06					-2 = Lead-Free Solder Charge
SEAM-GP	-S = 30 μ" (0.76 μm) Gold on contact area, Matte Tin on solder tail		-08						
			-10						





View complete specifications at: samtec.com?SEAM

Note: Some lengths, styles and options are non-standard, non-returnable

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

-  [View SEAF-30-01-L-06-2-RA-TR on WIN SOURCE](#)
-  [Samtec Inc. Information](#)

Optimize Your Supply Chain with WIN SOURCE Solutions

-  Global Sourcing Solution
-  Obsolete Management
-  Cost Control Management
-  Shortage Management
-  Alternative Solution
-  Excess Inventory Management